



3.5x2.8 mm INFRARED EMITTING DIODE

Features

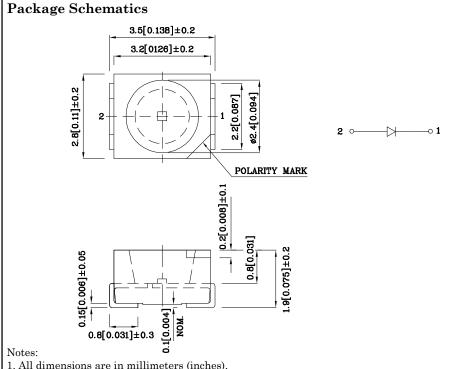
- Long life and robust package
- Standard Package: 2000pcs/ Reel
- \bullet MSL (Moisture Sensitivity Level): 3

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ullet RoHS compliant







- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.
- 3. Specifications are subject to change without notice.

Absolute Maximum Ratings (T _A =25°C)		TNI (GaAs)	Unit	
Reverse Voltage	$V_{\rm R}$	5	V	
Forward Current	I_{F}	50	mA	
Forward Current (Peak) 1/100 Duty Cycle 10us Pulse Width	i _{FS}	1200	mA	
Power Dissipation	P_D	80	mW	
Operating Temperature	T_{A}	-40 ~ +85	$^{\circ}\mathrm{C}$	
Storage Temperature	Tstg	-40 ~ +85	C	

A Relative Humidity between 40% and 60% is recommended in ESD-protected work areas to reduce static build up during assembly process (Reference JEDEC/JESD625-A and JEDEC/J-STD-033)

Operating Characteristics (T_A =25°C)	TNI (GaAs)	Unit		
Forward Voltage (Typ.) (I _F =20mA)	V_{F}	1.2	V	
Forward Voltage (Max.) (I _F =20mA)	V_{F}	1.6	V	
Reverse Current (Max.) $(V_R=5V)$	I_{R}	10	uA	
Wavelength of Peak Emission CIE127-2007* (Typ.) $(I_F=20\text{mA})$	λΡ	940*	nm	
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =20mA)	Δλ		nm	
Capacitance (Typ.) (V _F =0V, f=1MHz)	C	90	pF	

Part Number	Emitting Material	Lens-color	Radiant Intensity CIE127-2007* (Po=mW/sr) @20mA		Wavelength CIE127-2007* λP nm	Viewing Angle 20 1/2
			min.	typ.		
XZTNI45S	GaAs	Water Clear	1.6 1.2*	3.8 2.3*	940*	120°

^{*}Radiant intensity value and Wavelength are in accordance with CIE127-2007 standards.

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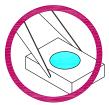
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Handling Precautions

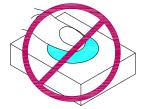
Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force.

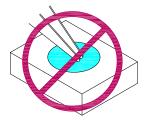
As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

1. Handle the component along the side surfaces by using forceps or appropriate tools.

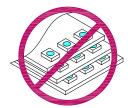


2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.

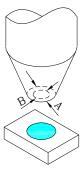




3. Do not stack together assembled PCBs containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry.



- 4.1. The inner diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks.
- 4.2. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.
- 4.3. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.

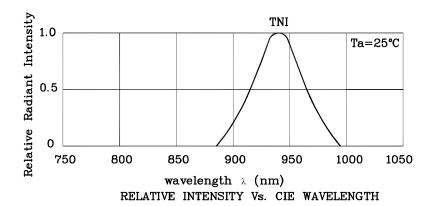


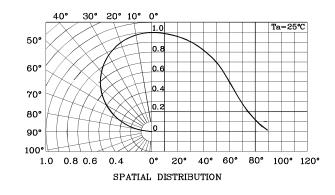
5. As silicone encapsulation is permeable to gases, some corrosive substances such as H_2S might corrode silver plating of leadframe. Special care should be taken if an LED with silicone encapsulation is to be used near such substances.

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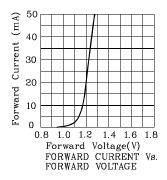


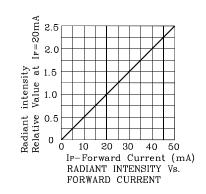


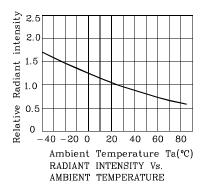




❖ TNI

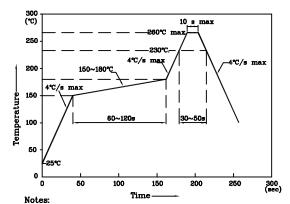






LED is recommended for reflow soldering and soldering profile is shown below.

Reflow Soldering Profile for SMD Products (Pb-Free Components)

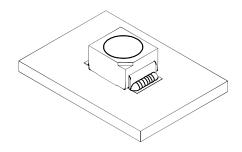


- 1. Maximum soldering temperature should not exceed 260°C
- 2. Recommended reflow temperature: 145°C-260°C
- 3. Do not put stress to the epoxy resin during high temperatures conditions

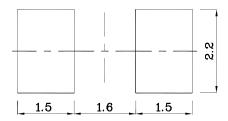




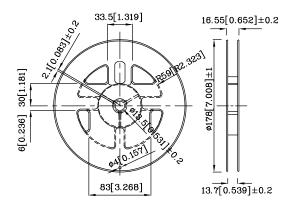
❖ The device has a single mounting surface. The device must be mounted according to the specifications.



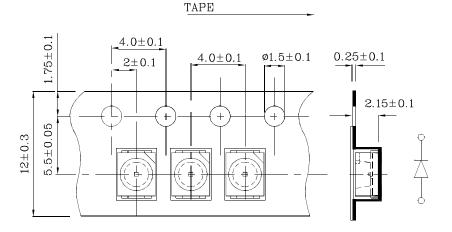
❖ Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)



❖ Reel Dimension



❖ Tape Specification (Units:mm)



Remarks:

If special sorting is required (e.g. binning based on forward voltage or radiant intensity / luminous flux), the typical accuracy of the sorting process is as follows:

- 1. Radiant Intensity / Luminous Flux: +/-15%
- 2. Forward Voltage: +/-0.1V

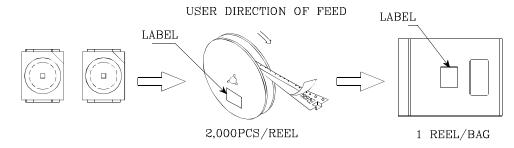
Note: Accuracy may depend on the sorting parameters

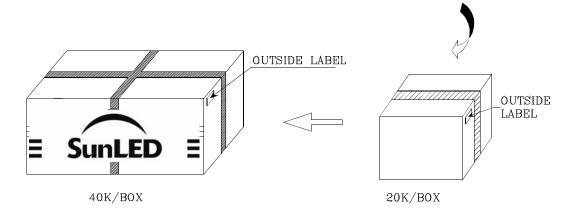


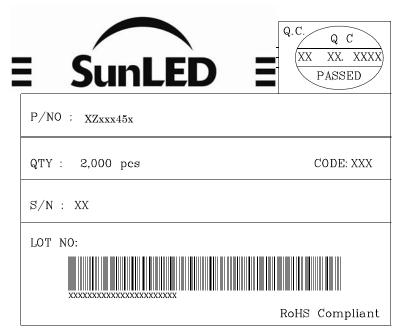
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PACKING & LABEL SPECIFICATIONS

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